

Add: 4-5/F Dadong Ming Technology Park, Yuequn Road, Changzhen, Guangming District, Shenzhen, China Tel: +86-0755-27350605 Fax: +86-0755-23245913 Web: www.color-led.com

## **Product specification**

Product N	No.:	LC88121	B-3535X			
Descripti	on: <u>3535</u>	SMD 0.2W inte	lligent extern	al control L	ED	
Date:		2020	-9-1		_	
Document No. SPC-TOP-A/20701						
Version <b>N</b>	No.:	A/2	20			
ELEC SENSIT	CE					
	Customer review	1	LED Color			
Approved	Confirm	Make	Approved	Confirm	Make	
			Mr Zhao	Mr Zhao	Mr Cheng	
Accept		Not accept	Date: 2020-9-1			

### **1.Product description:**

LC8812B-3535X is an intelligent externally controlled LED that integrates a control circuit and a light-emitting circuit. Its appearance is the same as a 3535 LED. Each LED is a pixel. The LED contains an intelligent digital interface data latch signal circuit. , Power supply voltage regulator circuit, built-in constant current circuit, data regeneration circuit, high precision RC oscillator, output drive adopts patented PWM technology, which effectively guarantees the color consistency of the each pixel.

The data protocol adopts a unipolar return-to-zero code communication method. After the LED is powered on, the DIN terminal receives external signal data, and the data regeneration circuit automatically reshapes and forwards the cascaded output data to ensure that the data is transmitted in series without attenuation and normal transmission .

LC8812B-3535X has the advantages of low voltage drive, environmental protection and energy saving, high brightness, large scattering angle, good consistency, long life and so on. The control circuit is integrated inside the LED, which makes the application circuit design easier, less original parts, and small in size. Beautiful, easier to install.

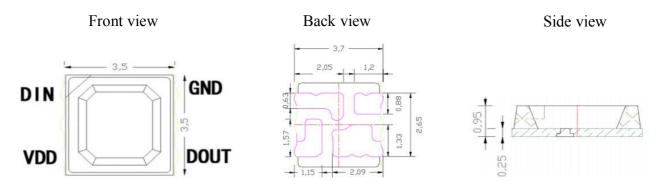
### 2.Main application areas:

LED full-color luminous character string light, LED full-color soft and hard light bar, LED point light source, LED pixel screen, LED special-shaped screen, LED full-color module, car lights, shoe lights, toys, audio, home appliances, and various electronics product.

### 3.Feature:

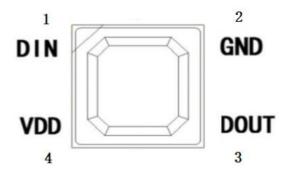
- Smart SMD integrates high-quality external control single-wire serial cascaded constant current IC.
- The control circuit and chip are integrated in SMD components to form a complete externally controlled pixel point, color,color temperature, uniform effect and high consistency,and the default output constant current value OUTW/OUTW/OUTW is 12MA
- Built-in data shaping circuit, any pixel point receives the signal after waveform shaping and then output to ensure that the signal waveform distortion will not accumulate. Data shaping: After receiving the data of this unit, the subsequent data will be shaped and output automatically.
- Built-in power-on reset and power-down reset circuits, the light does not light up after power-on.
- Single-wire data transmission, unlimited cascading, data sending rate 800Kbps synchronous refresh
- Grayscale adjustment circuit (256-level grayscale is adjustable).
- Vertical SMD surface mount package, suitable for all SMT assembly and soldering processes.
- Moisture-proof grade: LEVEL5a.
- CE, RoHS certification.

### 4. Package size drawing:



Remarks: All dimensions are marked in millimeters and the tolerance is  $\pm 0.15$  mm, unless otherwise specified.

### 5.Pin diagram and function description:



No.	Symbol	Function description
1	DIN	Control data signal input
2	GND	Ground
3	DOUT	Control data signal output
4	VDD	Power supply

### 6.White chip characteristic parameter Ta=25°C:

Color	Color Temperature	Light intensity(mcd)	Lumen (LM)	Ra	Product No.
ССТ	2800-3200K	-	12-16	≥90	LC8812B-3535WW
ССТ	3800-4200K	-	12-16	≥90	LC8812B-3535NW
ССТ	5800-6500K	-	12-16	≥90	LC8812B-3535W

## 7. Electrical parameters (limit parameters, unless otherwise specified, Ta=25°C):

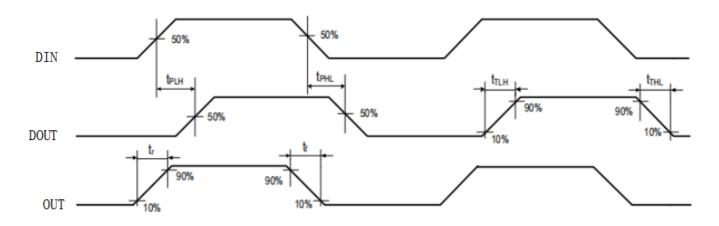
Parameter	Symbol	Range	Unit
Voltage	Vdd	+3.0~+5.5	V
Logic input voltage	VI	-0.4~VDD+0.4	V
Working temperature	Topt	-40~+85	°C
Storage temperature	Tstg	-50~+85	°C
ESD pressure (Device mode)	Vesd	200	V
ESD pressure (body model)	Vesd	4000	V

### 8.Electrical characteristics (if no special instructions, VDD=5V, Ta=25℃):

Parameter	Symbol	Min	Typical	Max	Unit	Test conditions
The chip supply Voltage	VDD	-	5.0	-	V	
W/W/W port pressure	VDS,MAX	-	-	26	V	
Quiescent Current	Idd	-	0.5	-	mA	VDD=4.5V, IOUT "OFF"
DOUT Output current	Іон	-	-40	-	mA	DOUT output high,Connect a $10\Omega$ resistor in series to GND
DOUT Sink current	Iol	-	40	-	mA	DOUT output low,Power sinks current to DOUT
	VIH	0.7	-	-	V	DIN Input high level
The Signal Input flip		*V				
threshold		DD				
	VIL	-	-	0.3*	V	DIN Input low level
				VDD		
OUT W/W/W Constant	VDS_S	-	0.7	-	V	IOUT = 12mA
current knee voltage						
	%VS.VDS	-	0.5	-	%	IOUT=12mA, VDS =1.0~3.0V
OUT W/W/W Output current	%VS.VDD	-	0.5	-	%	IOUT=12mA, VDD= 4.5~5.5V
change	%VS.TA	-	4.0	-	%	IOUT=12mA,TA=-40~+85°C
OUT W/W/W Port leakage	Ileak	-	-	1	uA	VDS =15V, IOUT"OFF"
current						
PWM Frequency	fрwм	-	1.2	-	KHZ	

### 9.Dynamic parameters (if no special instructions, VDD=5.0V, Ta=25℃):

Parameter	Symbol	Min	Typical	Max	Unit	Test conditions
The speed of data transmission	<b>f</b> din	-	800	-	KHz	Refer to LC8812B data communication diagram protocol
DOUT	<b>t</b> plh	-	80	-	ns	DOUTport load capacitance to ground C=30pF
transmission delay	<b>t</b> phl	-	80	-	ns	
Iout RiseTime	tr	-	50	-		IOUT R/G/B=12mA, OUT R/G/B port is connected with a 200 $\Omega$ resistor in series to VDD, and the load
	tſ	-	100	-		capacitance to ground is 15pF

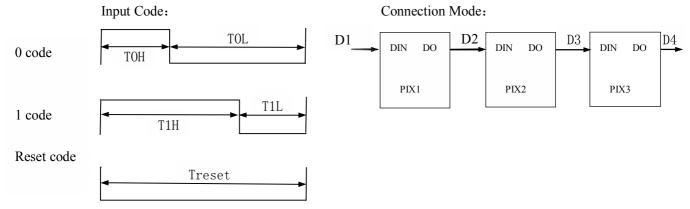


## 10.Data transmission time(TH+TL=1.25µs±600ns):

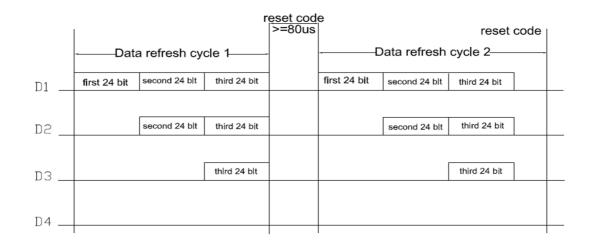
Name	Description	Min	Typical	Max	Allowable	Unit
					error	
T0H	0 code, high level time	-	0.3	-	±0.15	US
T1H	1 code, high level time	-	0.6	-	±0.15	US
T0L	0 code, low level time	-	0.9	-	±0.15	US
T1L	1 code, low level time	-	0.6	-	±0.15	US
TRST	Reset code, low level time	-	80	-	-	US

### **11.Coding timing diagram:**

The chip protocol uses a unipolar return-to-zero code, and each symbol must have a low level. Each symbol of this protocol starts with a high level, and the time width of the high level determines the "0" code or the "1" code.

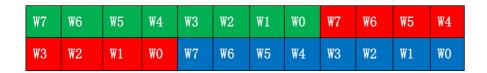


### 12.Data transmission method (Ta=25°C):



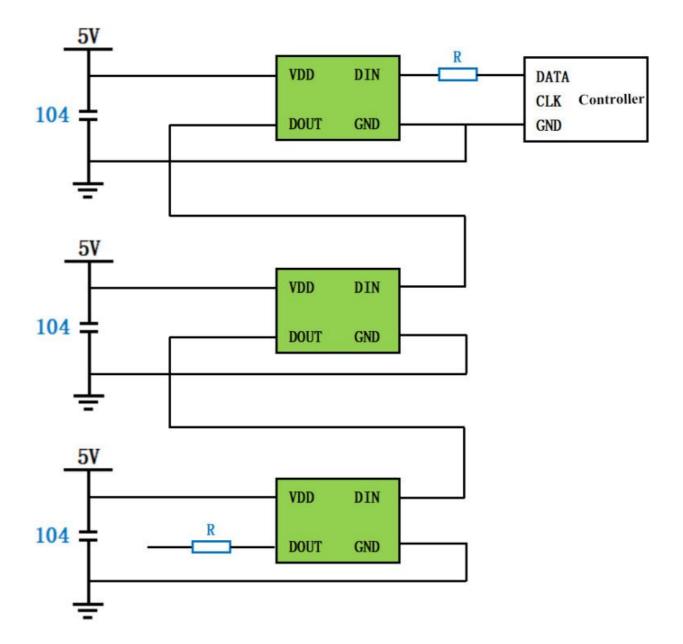
Note: D1 is the data sent by the MCU, and D2, D3, and D4 are the data that the cascade circuit automatically reshapes and forwards.

### 13.Data structure (Ta=25℃):



Note: The high bit is sent first, and the data is sent in the order of W7-W0 (W7  $\rightarrow$  W6  $\rightarrow$  .....W0).

## 14. Typical application circuit:

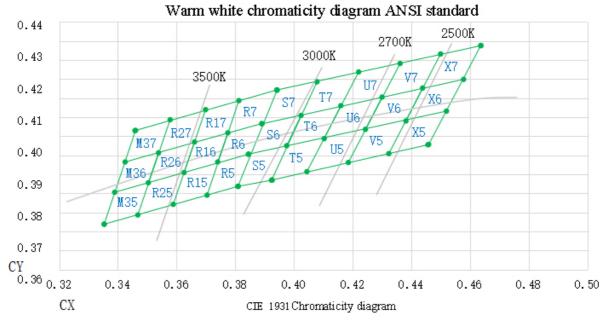


The signal input and output terminals of the product need to be connected in series when necessary. The size of the protective resistor R depends on the number of cascaded led. The more the number of cascades, the smaller the R. Generally, a value between 27-51 ohms is recommended. The recommended value is around 33 ohms.

### 15.Color temperature grade and CIE color grade division

(Refers to the 1931 CIE chromaticity diagram)

CIE Chromaticity Coordinates (ANS Energy Star)



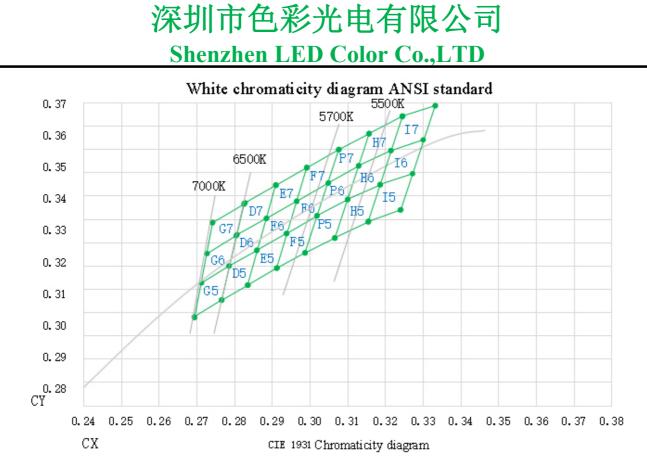
BIN	Cx	Су	BIN	Cx	Су	BIN	Cx	Су
	0.4786	0.4304		0.4731	0.4211		0.4677	0.4118
X7	0.4731	0.4211	X6	0.4677	0.4118	X5	0.4622	0.4025
	0.4837	0.4232	ло	0.4783	0.4139	лэ	0.4728	0.4026
	0.4891	0.4325		0.4837	0.4232		0.4783	0.4139
	0.4667	0.4281		0.4619	0.4189		0.4569	0.4096
V7	0.4619	0.4189	VG	0.4569	0.4096	<b>V</b> 5	0.4517	0.4004
V C	0.4731	0.4211	V6	0.4677	0.4118		0.4622	0.4025
	0.4786	0.4304		0.4731	0.4211		0.4677	0.4118
	0. 4551	0.4257		0.4509	0.4167		0.4467	0.4076
U7	0.4509	0.4167	UG	0.4467	0.4076		0.4425	0.3986
	0.4619	0.4189	U6	0.4517	0.4004	U5	0.4517	0.4004
	0.4667	0.4281		0.4569	0.4096		0.4569	0.4096
	0.4469	0.4228		0.4428	0.4138	- T5	0.4386	0.4048
T7	0.4428	0.4138	T6	0.4386	0.4048		0.4344	0.3957
11	0.4509	0.4167		0.4467	0.4076		0.4425	0.3986
	0. 4551	0.4257		0.4509	0.4167		0.4467	0.4076

					<u> </u>			
	0.4388	0.4200		0.4346	0.4109		0.4304	0.4019
S7	0.4346	0.4109	56	0. 4304	0.4019	OF.	0.4262	0.3928
51	0.4428	0.4138	S6	0.4386	0.4048	S5	0.4344	0.3957
	0.4469	0.4228		0.4428	0.4138		0.4386	0.4048
	0.4307	0.4171		0.4265	0.4081		0. 4223	0.3990
R7	0.4265	0.4081	DC	0. 4223	0.3990	DE	0.4181	0.3900
	0.4346	0.4109	R6	0.4304	0.4019	R5	0. 4262	0.3928
	0.4388	0.4200		0.4346	0.4109		0. 4304	0.4019
	0.4199	0.4138		0.4166	0.4041		0. 4123	0.3930
R17	0.4166	0.4041		0. 4123	0.3930		0.4092	0.3830
KI (	0.4265	0.4081	R15	0. 4223	0.3990	R15	0.4180	0.3900
	0.4307	0.4171		0.4265	0.4081		0. 4223	0.3990
	0.4096	0.4092		0.4062	0.3983		0. 4032	0.3880
D07	0.4062	0.3983	R26	0. 4032	0.3880	R25	0.4007	0.3778
R27	0.4166	0. 4041		0. 4123	0.3930		0. 4092	0.3830
	0. 4199	0.4138		0.4166	0.4041		0. 4123	0.3930

#### Nature white chromaticity diagram ANSI standard 0.40 3500K 0.39 4000K M2 0.38 4500K **M**7 120 0.37 5000K MG Κ7 0.36 Z7ME KC 07 0.35 Ζ6 17K5 06 0.34 75 ۵5 0.33 0.32 CY 0.32 0.30 0.34 0.36 0.38 0.40 0.42 СХ

CIE 1931 Chromaticity diagram

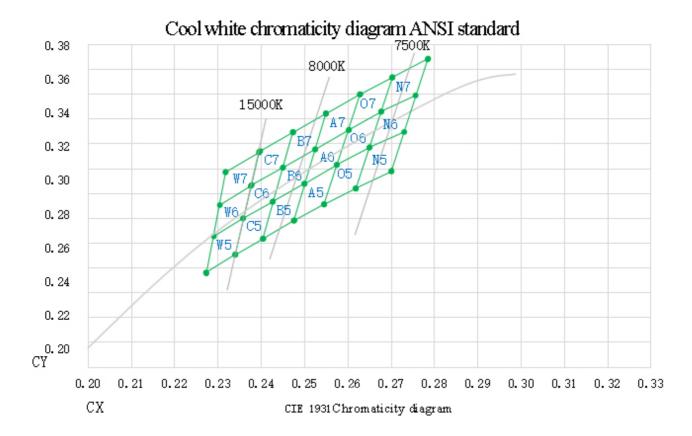
BIN	Cx	Су	BIN	Cx	Су	BIN	Cx	Су
	0.391	0.3983		0.3884	0.3881		0.3858	0.3779
M27	0.3884	0.3881	M26	0.3858	0.3779	M25	0.3832	0.3677
MZ (	0.3972	0.3971	MZO	0.3946	0.3828	M20	0.3921	0.3725
	0.3997	0.4033		0.3972	0.3971		0.3946	0.3828
	0.3825	0.3930		0.3799	0.3828		0.3773	0.3726
	0.3799	0.3828	MC	0.3773	0.3726	115	0.3747	0.3624
M7	0.3884	0.3881	M6	0.3858	0.3779	М5	0.3832	0.3677
	0.3910	0.3983		0.3884	0.3881		0.3858	0.3779
	0.3740	0.3877		0.3714	0.3775		0.3688	0.3673
17	0.3714	0.3775	L6	0.3688	0.3673	TE	0.3666	0.3575
L7	0.3799	0.3828		0.3773	0.3726	L5	0.3747	0.3624
	0.3825	0.3930		0.3799	0.3828		0.3773	0.3726
	0.3655	0.3824	K6	0.3629	0.3722	K5	0.3603	0.3620
. V7	0.3629	0.3722		0.3603	0.3620		0.3581	0.3522
K7	0.3714	0.3775		0.3688	0.3673		0.3666	0.3575
	0.3740	0.3877		0.3714	0.3775		0.3688	0.3673
	0.3565	0.3769		0.3563	0.3679		0.3560	0.3590
27	0.3563	0.3679	Z6	0.3560	0.3590	Z5	0.3554	0.3505
	0.3629	0.3722	20	0.3603	0.3620	20	0.3581	0.3522
	0.3655	0.3824		0.3629	0.3722		0.3603	0.3620
	0.3497	0.3706		0.3502	0.3631		0.3508	0.3557
Q7	0.3502	0.3631	Q6	0.3508	0.3557	<b>Q</b> 5	0.3459	0.3426
	0.3563	0.3679	40	0.3560	0.3590	40	0.3554	0.3505
	0.3497	0.3706		0.3563	0.3679		0.3560	0.3590
	0.3443	0.3650	J6	0.3448	0.3575	J5	0.3453	0.3501
J7	0.3448	0.3575		0.3453	0.3501		0.3402	0.3369
	0.3504	0.3632		0.3510	0.3558		0.3515	0.3483
	0.3499	0.3707		0.3504	0.3632		0.3510	0.3558



BIN	Cx	Су	BIN	Сх	Су	BIN	Сх	Су
	0.3386	0.3592		0.3392	0.3518		0.3397	0.3443
17	0.3392	0.3518	те	0.3397	0.3443	ТЕ	0.3402	0.3369
I7	0.3448	0.3575	16	0.3453	0.3501	15	0.3459	0.3426
	0.3443	0.3650		0.3448	0.3575		0.3453	0.3501
	0.3330	0.3535		0.3335	0.3461		0.3341	0.3386
H7	0.3335	0.3461	ис	0.3341	0.3386	H5	0.3346	0. 3312
	0.3392	0.3518	H6	0.3397	0.3443		0.3402	0.3369
	0.3386	0.3592		0.3392	0.3518		0.3397	0.3443
	0.3269	0.3553		0.3274	0.3478	DE	0.3279	0.3404
P7	0.3274	0.3478	P6	0.3279	0.3404		0.3284	0. 3329
F(	0.3335	0.3461	FO	0.3341	0.3386	P5	0.3346	0.3312
	0.3324	0.361		0.3335	0.3461		0.3341	0.3386
	0.3212	0.3495		0.3218	0.3421	- F5	0.3223	0.3346
F7	0.3218	0.3421	F6	0.3223	0.3346		0. 3228	0. 3272
	0.3274	0.3478		0.3279	0.3404		0.3284	0. 3329
	0.3269	0.3553		0.3274	0.3478		0.3279	0.3404

	深圳巾巴彩光电有限公司										
Shenzhen LED Color Co.,LTD											
	0.3156	0.3438		0.3161	0.3364		0.3167	0.3289			
E7	0.3161	0.3364	D.C.	0.3167	0.3289	DE	0.3172	0.3215			
E7	0. 3218	0.3421	E6	0. 3223	0.3346	E5	0.3228	0.3272			
	0.3212	0.3495		0.3218	0.3421		0.3223	0.3346			
	0.3100	0.3381	DC	0.3105	0.3307	DE	0.3110	0.3232			
D7	0.3105	0.3307		0.3110	0.3232		0.3115	0.3158			
Dí	0.3161	0.3364	D6	0.3167	0.3289	D5	0.3172	0.3215			
	0.3156	0.3438		0.3161	0.3364		0.3167	0.3289			
	0.3028	0.3293		0.3051	0.3181		0.3072	0.3081			
07	0.3051	0.3181	G6	0.3072	0.3081	G5	0.3107	0.2979			
G7	0.3108	0.3269		0.3117	0.3158		0.3146	0.3069			
	0.3100	0.3381		0.3108	0.3269		0.3117	0.3158			

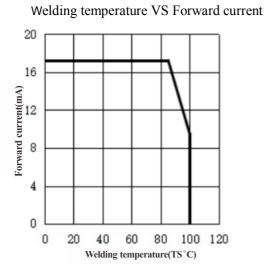
# 波圳市 布 必 业 由 右 阳 八 三



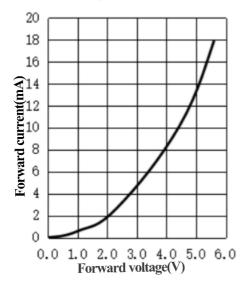
BIN	Cx	Су	BIN	Cx	Су	BIN	Cx	Су
N7	0.2963	0.3192	N6	0.2990	0.3088	N5	0.3022	0.2979
	0.2990	0.3088		0.3022	0.2979		0.3062	0.2884
	0.3051	0.3181		0.3072	0.3081		0.3107	0.2979
	0.3028	0.3293		0.3051	0.3181		0.3072	0.3081
07	0.2897	0.3072	06	0.2937	0.2978	05	0.2977	0.2883
	0.2937	0. 2978		0.2977	0.2883		0.3018	0.2789
	0.2990	0.3088		0.3022	0.2979		0.3062	0.2884
	0.2963	0.3192		0.2990	0.3088		0.3022	0.2979
A7	0.2779	0.3052	A6	0.2838	0.2914	A5	0.2897	0.2776
	0.2838	0.2914		0.2897	0.2776		0.2956	0.2638
	0.2908	0.3047		0.2967	0.2909		0.3025	0.2771
	0.2849	0.3185		0.2908	0.3047		0.2967	0.2909
	0.2709	0.2919	B6	0.2678	0.2781	<b>B</b> 5	0.2827	0.2643
D7	0.2678	0.2781		0.2827	0.2643		0.2886	0.2505
B7	0.2838	0.2914		0.2897	0.2776		0.2956	0.2638
	0.2779	0.3052		0.2838	0.2914		0.2897	0.2776
C7	0.2640	0.2648	C6	0.2698	0.2648	C5	0.2757	0.2510
	0.2698	0.2648		0.2757	0.2510		0.2816	0.2372
	0.2678	0.2781		0.2827	0.2643		0.2886	0.2505
	0.2709	0.2919		0.2678	0.2781		0.2827	0.2643
W7	0.2570	0.2653	W6	0.2629	0.2516	₩5	0.2687	0.2378
	0.2629	0.2516		0.2687	0.2378		0.2746	0.2240
	0.2629	0.2516		0.2757	0.2510		0.2816	0.2372
	0.2698	0.2648		0.2698	0.2648		0.2757	0.2510

Note: The above is the color photoelectric color zone diagram, which can only be used as a reference. The actual test results shall prevail.

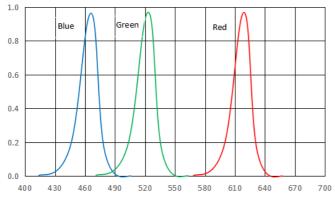
### 16. Typical optical characteristic curve:



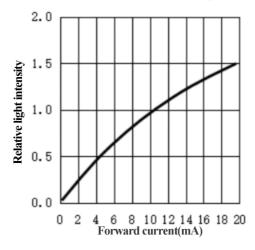
#### Forward voltage VS Forward current



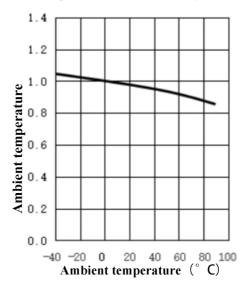
Relative spectral distribution chart



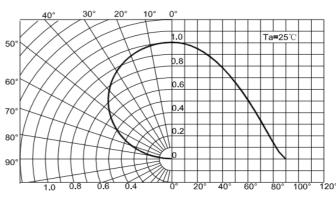
#### Forward current VS Relative light intensity



Ambient temperature VS Rrelative light intensity



#### Relative spectral distribution chart

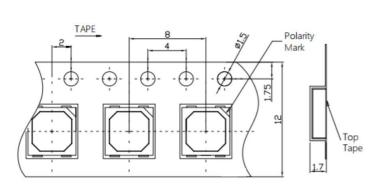


## 17.Reliability Test :

Test Item	Test Conditions	Duration/Cycle	Quantity	Ac/Re
Resistance to Soldering Heat	260°C/10sec	3 Min.	22PCS	0/1
Temperature cycle	-40°C 30min ↑↓25°C(5min) 100°C 30min	200 cycles	22PCS	0/1
Thermal Shock	-40°C 20min ↑↓ 10sec 100°C 20min	300 cycles	100PCS	0/1
High temperature and humidity storage	Ta=85°C RH=85%	1000 hours	22PCS	0/1
High Temperature Storage	Ta=100℃	1000 hours	22PCS	0/1
Low Temperature Storage	Ta=-40℃	1000 hours	22PCS	0/1
Room Temperature Operation life	Ta=25°C IF=Typical value	1000 hours	22PCS	0/1

### **18.**Packing specifications:

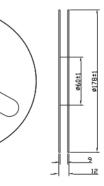
#### Carrier tape specifications (unit: mm)



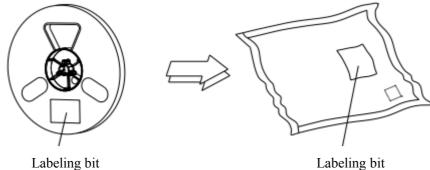
**Reel size:** 

2.2±0

ø13±0.5



#### Moisture-proof bag packaging:

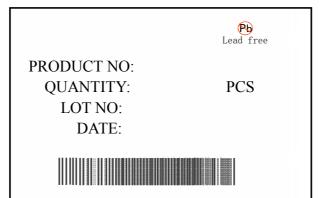


Labeling bit

Note: The marked tolerance is ±0.1mm, unit: mm

#### Label description:

PRODUCT No: Product model QUANTITY: Package quantity LOT NO: Order number DATE: Production date



Label diagram

Note: SMD3535 series packaging standard is 1500PCS/bag, except for special requirements.

### **SMD LED Usage Notice**

Thank you for using the LED chip of Shenzhen LED Color Co., Ltd.. In order to enhance your understanding of the characteristics of our products, and to facilitate you to quickly grasp the basic operations of the products, in order to minimize or avoid unnecessary products caused by human factors damaged, so that it can better serve your production, specially for some standard use in the process of use for corresponding instructions. At the same time even if the same specification LED, its reliability and design level in the actual application field, operation mode, use conditions They are all related. This instruction manual cannot cover all the problems that customers may encounter during use. We apologize for the inconvenience caused!

1.1 Generally, LEDs are used in the same way as other electronic components. In order to allow customers to better use our LED products, please refer to the following LED protection precautions.

1.2 Transportation and storage

Smart LED is packaged in a moisture-proof and anti-static aluminum foil bag. Avoid squeezing or piercing the packaging bag during transportation, and take necessary anti-static protection measures. Before the product is produced, if air leakage or damage is found, please stop using it directly and do the necessary use after high temperature dehumidification. In the process of product replacement, placement, finished product shipment, and installation, care should be taken to prevent external force from colliding and squeezing the LED, causing external force to damage the LED.

If the aluminum foil bag has been discovered before production, unsealed, damaged, or leaked, please return it to the original factory for dehumidification testing in time, and never use it online. Smart LED is a humidity-sensitive element. Packaging the LED in an aluminum foil bag is to prevent the LED from absorbing moisture during transportation and storage. A desiccant is placed in the packaging bag to absorb moisture. If the LED absorbs moisture, the moisture will expand when the LED is reflowed, causing the gel to separate from the bracket, or damage the key alloy wire, causing the product to fail. For this reason, the vacuum moisture-proof packaging is to avoid moisture in the packaging bag. The moisture-proof grade of this product is LEVEL5a.

Diagram 1: Definition of Material Moisture Resistance Level (MSL) specified by IPC/JEDEC J-STD-020

Moisture	Workshop life after unpacking			
Resistance level	Time	Condition		
LEVEL1	Unlimited	≦30°C/85 % RH		
LEVEL2	lyear	$\leq 30^{\circ}$ C/60 % RH		
LEVEL2a	4weeks	$\leq 30^{\circ}$ C/60 % RH		
LEVEL3	168hours	≦30°C/60 % RH		
LEVEL4	72hours	≦30°C/60 % RH		
LEVEL5	48hours	≦30°C/60 % RH		
LEVEL5a	24hours	$\leq$ 30°C/60 % RH		
LEVEL6	Take out and use	$\leq 30^{\circ}$ C/60 % RH		

#### 1.3.Storage before opening

In order to avoid redundancy failure caused by moisture absorption, it is necessary to take good measures to store and prevent moisture before LED products are produced.

If the vaccum moisture-proof bag is not opened, the storage time of Smart SMD components is within 1 month under

 $30^{\circ}C/60\%$ RH. (Subject to the date of the label, use the vacuum package without air leakage. There are certain differences in the storage time of different moisture-proof materials or packaging. The specific storage time is subject to the specification or the packaging bag.) It is recommended before use Do not open the vacuum packaging bag.

#### 1.4. SMT production control

After opening the packaging bag, the materials shall be strictly controlled within the allowable range of maximum humidity and operating time specified in diagram 1. As long as the material is exposed to the environment described in diagram 1, it must be used in the workshop. After opening the packaging bag and affixed to the PCB, the welding work should be completed within 2H. It is not recommended to stick the material on the PCB, and to stay in the workshop for a long time without SMT furnace operation, so as to prevent the material from absorbing the moisture in the solder paste and causing bad risks.

#### 1.5. Moisture-proof storage of unused materials

If a roll of led material has not been used up at one time, and the temperature and humidity of the workshop are within the limited conditions ( $\leq 30^{\circ}$ C/60%RH), and the exposure time of the element in the air does not exceed 2H, the remaining materials should be put into desiccant together. Vacuum and seal storage. Otherwise, the material must be baked and dehumidified at low humidity, and the dehumidified material can be repackaged to restart the calculation of time.

#### 1.6. Moisture-proof control for the assembled LED components

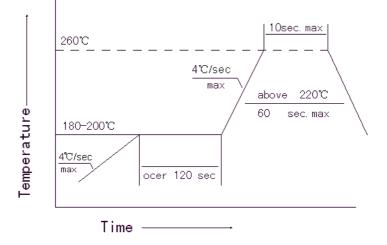
For products that require a secondary SMT process or high temperature, the necessary moisture-proof treatment should also be done before the secondary welding after the completion of the first welding. Exposure to ( $\leq 30^{\circ}C/60\%$ RH) conditions, the longest No more than 2H. If the time between the second high temperature production is longer, the material after the first welding must be dehumidified (bake in an oven at  $70^{\circ}C\pm5^{\circ}C$  for no less than 12 hours), and then vacuum sealed , or store the product in a constant temperature and humidity oven in a drying oven.Before the second high temperature production, do dehumidification work (bake in an oven at  $70^{\circ}C\pm5^{\circ}C$  for no less than 12 hours) to ensure that the product is not damp before the high temperature process. Low-humidity baking conditions:  $70^{\circ}C\pm5^{\circ}C$  for no less than 12 hours) to ensure that 12 hours; high-temperature baking conditions:  $130^{\circ}C\pm5^{\circ}C$  for 5 hours, and the total number of normal reflow soldering operations does not exceed 3 times.

For products subjected to extrusion process or high-temperature protection treatment, it is recommended that the necessary dehumidification work be done before the product is protected. Bake in an oven at  $130^{\circ}C \pm 5^{\circ}C$  for 5 hours to eliminate the moisture absorbed by the product during testing, aging, and transportation. In order to avoid the product after the protective treatment, the moisture wrapped on the surface of the material will slowly enter the material and cause the product to fail.

#### 1.7. Reflow soldering

It is verified by us using the parameters listed below that the surface mount LED meets the JEDEC J-STD-020C standard. As a general guideline, we recommende that customers follow the soldering temperature curve recommended by the manufacturer of the solder paste used.

Please note that this general guideline may not apply to all PCB designs and reflow soldering equipment configurations

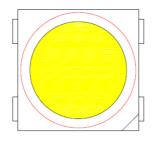


Profile Feature	Lead-Based Solder	Lead-Free Solder	
Average Ramp-Up Rate (Ts max to Tp )	3 °C/second max	3°C/second max	
Preheat: Temperature Min (Ts min )	100°C	150℃	
Preheat: Temperature Min (Ts max )	150°C	200°C	
Preheat: Time ( ts min to ts max )	60-120 seconds	60-180 seconds	
Time Maintained Above: Temperature (T L )	183 °C	217 °C	
Time Maintained Above: Time (t L)	60-150 seconds	60-150 seconds	
Peak/Classification Temperature (T P)	215 °C	240 °C	
Time Within 5℃ ℃ of Actual Peak	<10 seconds	<10 seconds	
Temperature (tp)			
Ramp-Down Rate	6 °C/second max	6 °C/second max	
Time 25 °C °C to Peak Temperature	<6 minutes max	<6 minutes max	

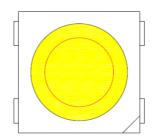
Note: All the Note: All the temperature refer to topside of the package, measured on the package body surface. When welding, do not forcefully press the surface of the colloid when the material is heated.

#### 1.8.SMT nozzle requirements:

(red circle refers to the inside diameter of the nozzle, see picture 1 and picture 2)



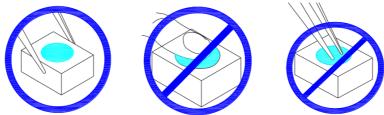
OK (the inside diameter of the nozzle is larger than the light-emitting area of the led)



NG (the inside diameter of the nozzle is smaller than the lighting area of the led)

In order to prevent air pressure leakage, the outer diameter of the SMD nozzle should not exceed the size of the LED, and the inner diameter of the nozzle should be as large as possible. The tip of the nozzle should be made of soft material to prevent scratching or damaging the LED gel surface during suction. The size of the component must be Accurate in the pick and place machine.

1.9. Material picking method: use tweezers to pick up the material. Do not press the colloid or sharp objects to puncture the colloid. The materials cannot be stacked.



Do not stack products together, it may damage the internal circuit,

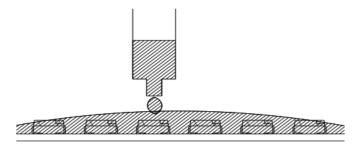


Cannot be used in acidic places with PH<7





2.0. When we need to use the external sealant to coat the LED products, we should ensure that the external sealant matches the LED packaging glue, because most of the LED packaging glue is silica gel and epoxy glue, it has oriented oxidation and aligned moisture absorption. It is necessary to prevent the external sealing material from entering the LED to cause damage to the LED. The content of a single bromine element is required to be less than 900PPM, and the content of a single chlorine element is required to be less than 900PPM. When applying LED products, the total content of bromine and chlorine in the outer sealant must be less than 1500PPM.



#### 2.1. Welding

For manual soldering, it is recommended to use an electric soldering iron with a power of not more than 60W, and control the temperature of the soldering iron not to exceed 350°C. The electric soldering iron stays on the bracket pin for no more than 3 seconds each time. If you need to repeatedly solder, the interval stay time is not less than 3 seconds to avoid long time high temperature damage to the LED.

During the soldering process, please do not touch or squeeze the surface of the LED to avoid damage to the LED interior. At the same time, please pay attention to avoid scalding and other damages to the LED surface colloid and PPA by the soldering iron.

#### 2.2. Thermal design requirements

For LED products, the design of heat dissipation is very important. When designing the product, please consider the heat generated by the LED, the thermal resistance of the PCB board, the density of the LED arrangement, and the input electric power will all increase the temperature.

In order to avoid excessive heat generation, it is necessary to ensure that the LED runs within the maximum specification range required in the product specification. When setting the driving power of the LED, the highest ambient temperature should be considered.

The maximum working temperature of the product cannot exceed 50°C (ie  $\leq$ 50°C, which refers to the operating temperature at the GND of the LED pin).

#### 2.3. Anti-static and surge protection for IC devices

Static electricity and surges can damage the LED products of IC devices. Therefore, corresponding protective measures must be taken. The signal input and output ports of the IC device are connected with protective resistors in series to prevent the product from failing due to surge or electrostatic shock.

In order to protect the LED products of IC devices, no matter what time or occasion, as long as you touch the LED, you need to wear an anti-static wristband and anti-static gloves. All equipment and instruments must be grounded.

It is recommended that each product is inspected before shipment, and there should be related electrical tests to select defective products caused by static electricity. When designing the circuit, consider eliminating the possibility of surges from harming LEDs.

#### 2.4. Special statement

1. If it is used outside of the specification, our company will not be responsible for any problems.

2. The LED can emit a strong light that can damage the eyes. Take precautions and do not look directly at the LED light with the naked eye for too long.

3. Before mass use, you should communicate with relevant personnel of our company to understand more detailed specifications.

4. If the shape and specifications of LED products are changed, please forgive me for not being able to inform in time.